

SSM9975GM-VB Datasheet

Dual N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
60	0.012 at V _{GS} = 10 V	10	15 nC		
60	0.015 at V _{GS} = 4.5 V	9.0	10 110		

FEATURES

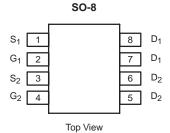




ROHS

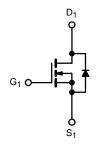
HALOGEN FREE

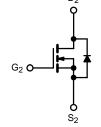
- Trench Power MOSFET
- 100 % UIS Tested
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

- Set Top Box
- Low Current DC/DC





N-Channel MOSFET

N-Channel MOSFET

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V _{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	V
	T _C = 25 °C		10 ^a	
Continuous Drain Current (T _{.I} = 150 °C)	$T_C = 70 ^{\circ}C$	I _D	8.2	
Commission (1) = 100 °C)	T _A = 25 °C	υ.υ	7.2 ^{b, c}	
	T _A = 70 °C		6.2 ^{b, c}	Α .
Pulsed Drain Current		I _{DM}	40	^
Continuous Source-Drain Diode Current	T _C = 25 °C	la	2.25	
	T _A = 25 °C	Is -	1.48 ^{b, c}	
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	30	
Single Pulse Avalanche Energy	L = 0.111111	E _{AS}	55	mJ
	T _C = 25 °C		2.7	
Maximum Dawar Dissination	T _C = 70 °C	P _D	4.77	W
Maximum Power Dissipation	T _A = 25 °C		2.78 ^{b, c}	VV
	T _A = 70 °C		1.14 ^{b, c}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c, d}	t ≤ 10 s	R _{thJA}	58	70	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{th.IF}	38	45	C/ VV		

Notes:

- a. Package limited, T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 110 °C/W.



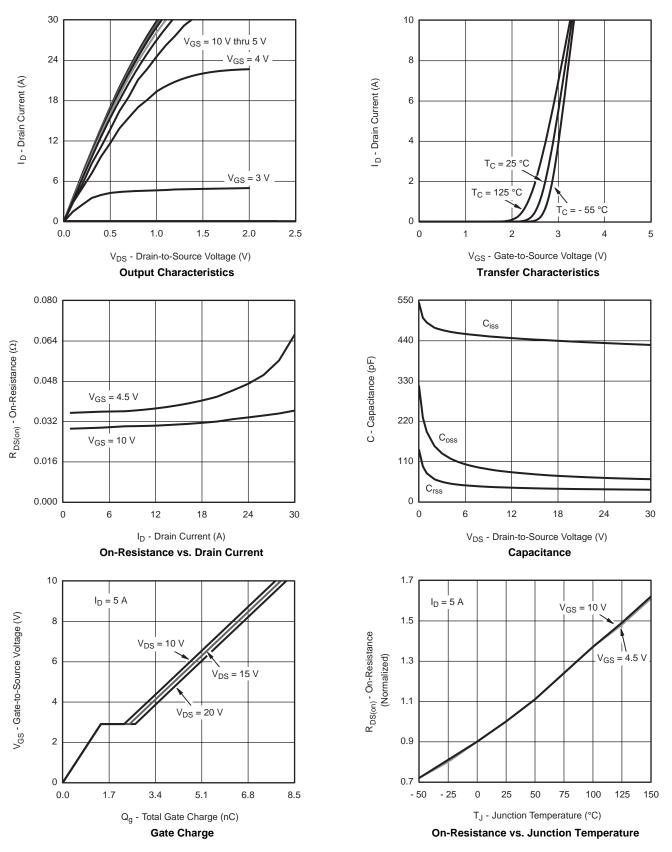
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		32		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.0			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			1	μΑ	
Zero Gate Voltage Drain Current	IDSS				10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
		$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.012		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.015			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5 A		16		S	
Dynamic ^b				1		_	
Input Capacitance	C _{iss}			586			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		217		pF	
Reverse Transfer Capacitance	C _{rss}			155			
Total Cata Charge	0	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		15	25		
Total Gate Charge	Q _g		6.7	9.6			
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		4.4	6.0	nC	
Gate-Drain Charge	Q_{gd}			3.05	4.0		
Gate Resistance	R _g	f = 1 MHz	0.8	4.3	8.6	Ω	
Turn-On Delay Time	t _{d(on)}			12	24		
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		55	100		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		11	22		
Fall Time	t _f			8	16		
Turn-On Delay Time	t _{d(on)}			4	8	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		9	18	- - -	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 10 V, R_g = 1 Ω		10	20		
Fall Time	t _f			6	12		
Drain-Source Body Diode Characteristi	cs		•	•	•		
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			2.25	۸	
Pulse Diode Forward Current	I _{SM}				24	A	
Body Diode Voltage	V_{SD}	I _S = 2 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			11	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 5 A, dI/dt = 100 A/μs, T _{.I} = 25 °C		4	8	nC	
Reverse Recovery Fall Time	t _a	$I_F = 3 \text{ A}$, $I_J = 25 \text{ C}$		7			
Reverse Recovery Rise Time	t _b	_		4	İ	ns	

Notes:

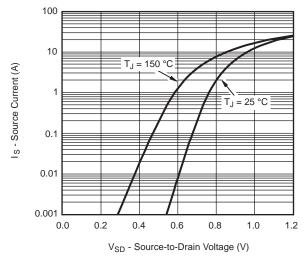
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

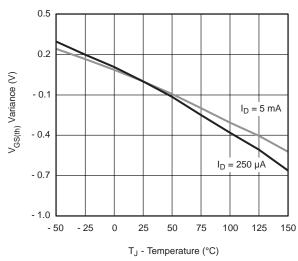




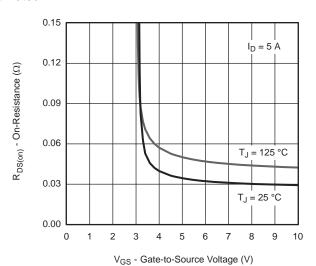




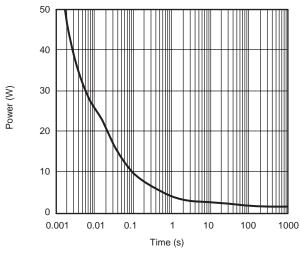
Source-Drain Diode Forward Voltage



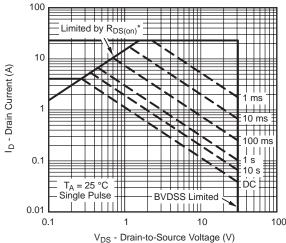
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



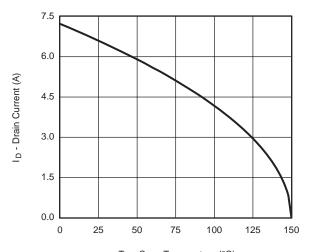
Single Pulse Power



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

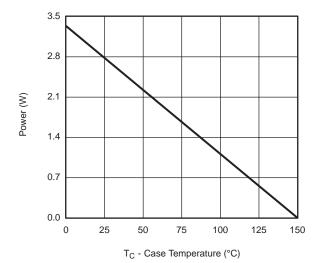
Safe Operating Area, Junction-to-Ambient

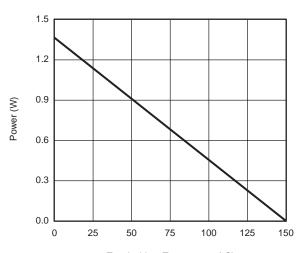




T_C - Case Temperature (°C)

Current Derating*





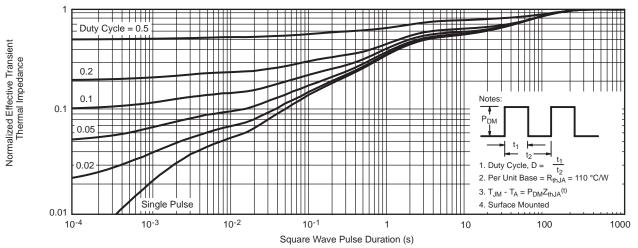
T_A - Ambient Temperature (°C)

Power, Junction-to-Foot

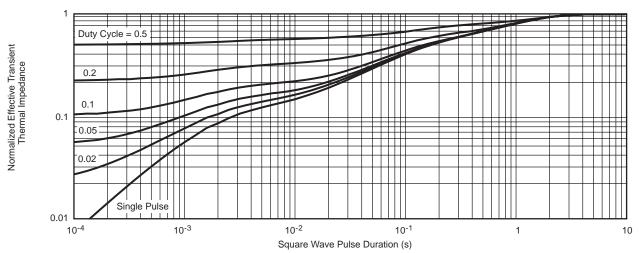
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





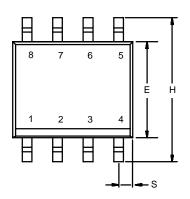
Normalized Thermal Transient Impedance, Junction-to-Ambient

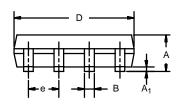


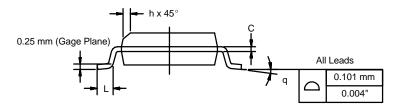
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







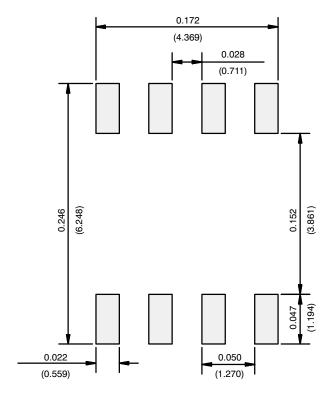
	MILLIN	IETERS	INC	HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Pey I 11-Sep-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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